



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/797,504

Filed: March 10, 2004

For: METHODS RELATING TO
SINGULATING SEMICONDUCTOR
WAFERS AND WAFER SCALE
ASSEMBLIES (as amended)

Confirmation No.: 3972

Examiner: H. Lee

Group Art Unit: 2823

Attorney Docket No.: 2269-5527US
(99-0440.00/US)

Notice of Allowance Mailed:

June 5, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV 826302645 US

Date of Deposit with USPS: August 24, 2006

Person making Deposit: Wendy Neff

TRANSMITTAL LETTER

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant submits herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1,715.00 in payment therefor plus five (5) copies of the patent when issued.

Also, enclosed is an Amendment Pursuant to 37 C.F.R. § 1.312(a) (14 pages), Comments on Statement of Reasons for Allowance (2 pages); and Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages).

Applicant understands that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,



Craig Buschmann
Registration No. 57,829
Attorney for Applicant(s)
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: August 24, 2006
CB/nj:eg

Enclosures: Part B - Issue Fee Transmittal
Check No. 23117 in the amount of \$1,715.00
Copy of Transmittal Letter
Amendment Pursuant to 37 C.F.R. § 1.312(a) (14 pages)
Comments on Statement of Reasons for Allowance (2 pages)
Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)



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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

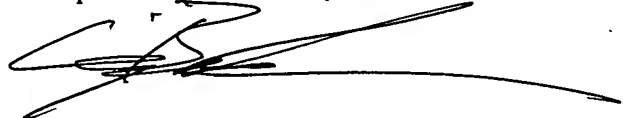
The Examiner indicates:

The prior art of record at least neither teaches nor suggests "cutting from the active surface of the semiconductor wafer body through the semiconductor wafer body with at least one laser beam along the plurality of streets between the active surface of the semiconductor wafer body and the at least one trench" and

“traversing the at least one laser beam to impinge the semiconductor wafer body along a path and substantially concurrently traversing the at least another laser beam to impinge the semiconductor wafer body along the same path subsequent to impingement of the at least one laser beam.”

Applicant concurs with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, the independent claims as allowed include other and different language than that specified by the Examiner, and the allowed dependent claims include other and further features and elements. Accordingly, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,



Craig Buschmann
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Telephone: 801-532-1922

Date: August 24, 2006

CB/aw:eg

Document in ProLaw